



100% Material Declaration Data Sheet BGG352

PK196 (v1.0.1) January 8, 2007

Material Declaration Data Sheet

Average Weight: 7.032g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					0.0291	0.41%
	Silicon	7440-21-3	100.00		0.0291	
Die Attach Material					0.004	0.05%
	Resin	Trade Secret	25.00		0.001	
	Silver	7440-22-4	75.00		0.003	
Mold Compound					0.2374	3.38%
	Resin	Trade Secret	26.00		0.062	
	Silica	60676-86-0	74.00		0.176	
Dam					0.0088	0.12%
	Proprietary	Trade Secret	27.00		0.002376	
	Silica	60676-86-0	73.00		0.006424	
Laminate					0.647	9.06%
	Copper	7440-50-8		Metal Layer	0.101	
	Nickel	7440-02-0		Metal Layer	0.006	
	Gold	7440-57-5		Metal Layer	0.002	
	Board	Trade Secret			0.396	
	Solder Mask (EP)	Trade Secret			0.142	
Heat Sink					5.252	74.85%
	Copper	7440-50-8	100.00		5.252	
Heat Sink Plating					0.2243	3.19%
	Nickel	7440-02-0	100.00		0.2243	
Gold Wire					0.0224	0.32%
	Gold	7440-57-5	100.00		0.0224	
Solder Balls					0.606	8.62%
	Tin	7440-31-5	95.50		0.579	
	Silver	7440-22-4	4.00		0.024	
	Copper	7440-50-8	0.50		0.003	

PK196 (v1.0.1) January 8, 2007

www.xilinx.com

1

Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
10/5/06	1.0	Initial release.
1/8/07	1.0.1	Corrected Gold Wire CAS# entry.